



SLOVENSKI STANDARD SIST EN IEC 61188-6-4:2019

01-november-2019

**Plošče tiskanih vezij in sestavi plošč tiskanih vezij - Zasnova in uporaba - 6-4. del:
Razmestitev priključkov - Splošne zahteve za merske risbe elementov za
površinsko montažo (SMD) glede na razmestitev njihovih priključkov**

Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

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EUROPEAN STANDARD

EN 61188-6-4

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Printed boards and printed board assemblies - Design and use -
Part 6-4: Land pattern design - Generic requirements for
dimensional drawings of surface mounted components (SMD)
from the viewpoint of land pattern design
(IEC 61188-6-4:2019)

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-4: Conception de la zone
de report - Exigences génériques pour les dessins
dimensionnels de composants montés en surface (CMS) du
point de vue de la conception de la zone de report
(IEC 61188-6-4:2019)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-4: Allgemeine Anforderungen an SMD-
Maßzeichnungen hinsichtlich der Konstruktion des
Anschlussflächenbilds
(IEC 61188-6-4:2019)

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Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN 61188-6-4:2019 (E)**European foreword**

The text of document 91/1561/FDIS, future edition 1 of IEC 61188-6-4, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61188-6-4:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-03-06
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-06-06

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60191-1	NOTE	Harmonized as EN IEC 60191-1
IEC 60191-6	NOTE	Harmonized as EN 60191-6
IEC 60191-6-1	NOTE	Harmonized as EN 60191-6-1
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191-1	NOTE	Harmonized as EN IEC 61191-1
IEC 61191-2	NOTE	Harmonized as EN 61191-2

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Terms and definitions for printed circuits	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-

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IEC 61188-6-4

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Printed boards and printed board assemblies – Design and use –
Part 6-4: Land pattern design – Generic requirements for dimensional drawings
of surface mounted components (SMD) from the viewpoint of land pattern
design**

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**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-4: Conception de la zone de report – Exigences génériques pour les
dessins dimensionnels de composants montés en surface (CMS) du point
de vue de la conception de la zone de report**

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CONTENTS

FOREWORD	4
1 Scope	6
2 Normative references	6
3 Terms, definitions and symbols	6
4 Applicable SMDs	8
5 Requirements	9
5.1 Figures and dimensional symbols	9
5.2 Common requirements	9
5.2.1 General	9
5.2.2 Requirements for solder joint fillet design	9
5.2.3 Requirements for courtyard design	10
5.2.4 Height parameters	10
5.2.5 Bottom view	12
5.2.6 Detail view	12
5.2.7 Distinguish between metal and resin	12
5.2.8 Consistency of various dimensions	12
5.2.9 The relation between a land pattern and an element-placement position	13
5.2.10 Coplanarity	14
5.3 Requirements for a specific SMD	14
5.3.1 General	14
5.3.2 End-terminal type	14
5.3.3 Gull-wing terminals type, inward L-shaped ribbon terminals type and under-body L type	18
5.3.4 Bottom surface terminal type and flat lug terminals type	30
6 Supplementary dimensions	39
Bibliography	40
Figure 1 – Example of the dimensional relationship to the drawings of SMDs, the land pattern design and the after soldering state	12
Figure 2 – Example of dimensional consistency for an asymmetrical SMD	13
Figure 3 – Example of the direction of recommendation for land pattern position of an asymmetrical SMD	14
Figure 4 – Influence of good and bad (after soldering) coplanarity	14
Figure 5 – Example of the dimensional relationship between the drawings of components with rectangular terminals and the land pattern design	16
Figure 6 – Example of the dimensional notations for a component with rectangular terminals	17
Figure 7 – Example of the dimensional notations for cylindrical components with end cap terminals	18
Figure 8 – Example of the dimensional relationship between the drawings of gull-wing terminals type and the land pattern design	19
Figure 9 – Example of the dimensional notations for gull-wing terminals type (QFP)	20
Figure 10 – Details of terminal (case 1)	21
Figure 11 – Details of terminal (case 2)	22
Figure 12 – Details of terminal (case 3)	22

Figure 13 – Details of terminal (case 4)	23
Figure 14 – Details of terminal (case 5)	23
Figure 15 – Example of the dimensional relationship between the drawings of inward L-shaped ribbon terminals type and the land pattern design.....	24
Figure 16 – Example of the dimensional notations for inward L-shaped ribbon terminals type	25
Figure 17 – Example of the dimensional notations for under-body L type	26
Figure 18 – Terminal shape expansion drawing of under-body L type (capacitor).....	27
Figure 19 – Example of the dimensional notations for a connector	28
Figure 20 – The cross-sectional a-a detail (terminal shape) of Figure 18, side view	29
Figure 21 – Example of the drawing showing the moving range (lock lever open state).....	29
Figure 22 – Example of the upper surface cap constitution	29
Figure 23 – Example of the dimensional relationship between the drawings of a BGA and the land pattern design.....	31
Figure 24 – Example of the dimensional notations for BGA.....	32
Figure 25 – Example of details of solder balls (side view)	33
Figure 26 – Example of the dimensional relationship between the drawings of QFN and the land pattern design	34
Figure 27 – Example of the dimensional notations for bottom surface terminals	36
Figure 28 – Example of the dimensional relationship between the drawings of flat lug terminals type and the land pattern design.....	38
Figure 29 – Example of the dimensional notations for flat lug terminals type	39
Figure 30 – Example of the recommended dimensions in the tray	39
Table 1 – Reference symbols used in this document.....	7

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**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –
DESIGN AND USE –**
**Part 6-4: Land pattern design – Generic requirements for dimensional
drawings of surface mounted components (SMD) from the viewpoint of
land pattern design**

FOREWORD

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International Standard IEC 61188-6-4 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

1 Scope

This part of IEC 61188 specifies generic requirements for dimensional drawings of SMD from the viewpoint of land pattern design.

The purpose of this document is to prevent land pattern design issues caused by lack of information and/or misuse of the information from SMD outline drawing as well as to improve the utilization of IEC 61188 series.

This document is applicable to the SMD of semiconductor devices and electrical components.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60194-2, *Printed board design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

3 Terms, definitions and symbols

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60194-2 apply, and the reference symbols are shown in Table 1.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

Table 1 – Reference symbols used in this document

Reference symbol	Definition
A	SMD height (from the mounting surface to the package upper surface)
A_1	Stand-off height (distance from the mounting surface to the package bottom)
A_2	Package height
A_3	Standard heel height for terminal
A_4	Terminal height
A_5	Terminal height (thickness)
A_6	SMD height (from the mounting surface to the package upper surface, maximum)
A_7	SMD height from the mounting surface to the package top (excluding moving part)
A_8	SMD height from the mounting surface to the package top (at the lock lever open state)
A_9	SMD height from the mounting surface to the upper surface of cap
$\varnothing b_1$	Terminal diameter for ball
$\varnothing b_2$	Ball diameter
C, C_1, C_2	Row spacing. Distance between land centers
CY_1	Courtyard width
CY_2	Courtyard length
D	Package width
D'	Solder balls area width (distance between the centres of the ball of both ends)
E	Package length
E'	Solder balls area length (distance between the centres of the ball of both ends)
E_2	Position of auxiliary terminals
E_3	Upper surface cap width
F_1, F_2	Clearance between signal and center (GND) terminal
F_3	Distance from package-end to terminal-end of signal terminal
F_4	Distance between signal terminals at the package corners
G, G_1, G_2	Distance between lands. Measured from inside edges
H_D	SMD total width
H_E	SMD total length
H_T	Height from the tray stage to the package top
i	Terminal inflection point
J_b	Protrusion length of land over the component terminal
J_H	Heel protrusion length
J_S	Side protrusion length
J_T	Toe protrusion length
k_1, k_2, k_4	Land pattern length
k_3	Distance between land patterns
K_5, K_6	Terminal notch length (toe)
K_7, K_8	Terminal notch height (heel)
L	Terminal flat part length (mounting surface side)
L_0, L_1	Length from the package end to a terminal tip
L_3	Position of auxiliary terminals
L_4	Auxiliary terminal pitch
L_5	Package length at the lock lever open state